

NB6L11M

2.5V / 3.3V 1:2 Differential CML Fanout Buffer

Multi-Level Inputs w/ Internal Termination

Description

The NB6L11M is a differential 1:2 CML fanout buffer. The differential inputs incorporate internal 50 Ω termination resistors that are accessed through the V_T pins and will accept LVPECL, LVCMOS, LVTTTL, CML, or LVDS logic levels.

The V_{REFAC} pin is an internally generated voltage supply available to this device only. V_{REFAC} is used as a reference voltage for single-ended PECL or NECL inputs. For all single-ended input conditions, the unused complementary differential input is connected to V_{REFAC} as a switching reference voltage. V_{REFAC} may also rebias capacitor-coupled inputs. When used, decouple V_{REFAC} with a 0.01 μF capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{REFAC} output should be left open.

The device is housed in a small 3x3 mm 16 pin QFN package.

The NB6L11M is a member of the ECLinPS MAX™ family of high performance clock products.

Features

- Maximum Input Clock Frequency > 4 GHz, Typical
- 225 ps Typical Propagation Delay
- 70 ps Typical Rise and Fall Times
- 0.5 ps maximum RMS Clock Jitter
- Differential CML Outputs, 380 mV peak-to-peak, typical
- LVPECL Operating Range: V_{CC} = 2.375 V to 3.63 V with V_{EE} = 0 V
- NECL Operating Range: V_{CC} = 0 V with V_{EE} = -2.375 V to -3.63 V
- Internal Input Termination Resistors, 50 Ω
- VREFAC Reference Output
- Functionally Compatible with Existing 2.5 V / 3.3V LVEL, LVEP, EP, and SG Devices
- -40°C to +85°C Ambient Operating Temperature
- These are Pb-Free Devices



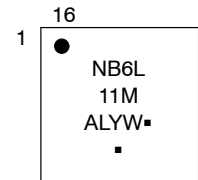
ON Semiconductor®

<http://onsemi.com>



QFN-16
MN SUFFIX
CASE 485G

MARKING DIAGRAM*



- A = Assembly Location
 - L = Wafer Lot
 - Y = Year
 - W = Work Week
 - = Pb-Free Package
- (Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

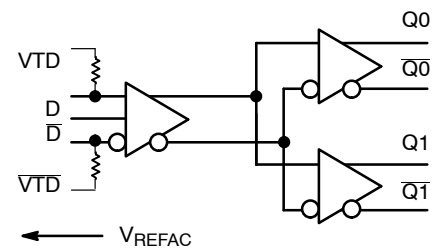


Figure 1. Simplified Logic Diagram

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

NB6L11M

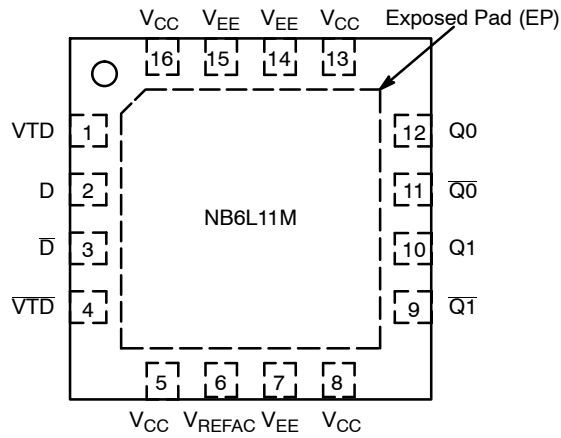


Figure 2. Pin Configuration (Top View)

Table 1. PIN DESCRIPTION

Pin	Name	I/O	Description
1	VTD	-	Internal 50 Ω Termination Pin for D input.
2	D	ECL, CML, LVCMOS, LVDS, LVTTTL Input	Noninverted Differential Input. Note 1. Internal 50 Ω Resistor to Termination Pin, VTD.
3	\bar{D}	ECL, CML, LVCMOS, LVDS, LVTTTL Input	Inverted Differential Input. Note 1. Internal 50 Ω Resistor to Termination Pin, \bar{VTD} .
4	\bar{VTD}	-	Internal 50 Ω Termination Pin for \bar{D} input.
5	VCC	-	Positive Supply Voltage
6	VREFAC		Output Reference Voltage for direct or capacitor coupled inputs
7	VEE	-	Negative Supply Voltage
8	VCC	-	Positive Supply Voltage
9	$\bar{Q1}$	CML Output	Inverted Differential Output. Typically Terminated with 50 Ω Resistor to VCC.
10	Q1	CML Output	Noninverted Differential Output. Typically Terminated with 50 Ω Resistor to VCC.
11	$\bar{Q0}$	CML Output	Inverted Differential Output. Typically Terminated with 50 Ω Resistor to VCC.
12	Q0	CML Output	Noninverted Differential Output. Typically Terminated with 50 Ω Resistor to VCC.
13	VCC	-	Positive Supply Voltage
14	VEE	-	Negative Supply Voltage
15	VEE	-	Negative Supply Voltage
16	VCC	-	Positive Supply Voltage
-	EP	-	The Exposed Pad (EP) on the QFN-16 package bottom is thermally connected to the die for improved heat transfer out of package. The exposed pad must be attached to a heat-sinking conduit. The pad is not electrically connected to the die, but is recommended to be electrically and thermally connected to VEE on the PC board.

1. In the differential configuration when the input termination pins (VTD, \bar{VTD}) are connected to a common termination voltage or left open, and if no signal is applied on D/ \bar{D} input, then, the device will be susceptible to self-oscillation.
2. All VCC and VEE pins must be externally connected to a power supply for proper operation.

NB6L11M

Table 2. ATTRIBUTES

Characteristics		Value
ESD Protection	Human Body Model Machine Model	> 2 kV > 200V
Moisture Sensitivity	16-QFN	Level 1
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
Transistor Count		
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test		

For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	Positive Power Supply	$V_{EE} = 0\text{ V}$		4.0	V
V_{EE}	Negative Power Supply	$V_{CC} = 0\text{ V}$		-4.0	V
V_{IO}	Positive Input/Output Voltage Negative Input/Output Voltage	$V_{EE} = 0\text{ V}$ $V_{CC} = 0\text{ V}$	$-0.5 \leq V_{Io} \leq V_{CC} + 0.5$ $+0.5 \leq V_{Io} \leq V_{EE} - 0.5$	4.0 -4.0	V V
V_{INPP}	Differential Input Voltage $[D - \bar{D}]$			$V_{CC} - V_{EE}$	V
I_{IN}	Input Current Through R_T (50 Ω Resistor)	Static Surge		45 80	mA mA
I_{OUT}	Output Current (CML Output)	Continuous Surge		25 50	mA mA
I_{VREFAC}	VREFAC Sink/Source Current			± 0.5	mA
T_A	Operating Temperature Range	16 QFN		-40 to +85	$^{\circ}\text{C}$
T_{stg}	Storage Temperature Range			-65 to +150	$^{\circ}\text{C}$
θ_{JA}	Thermal Resistance (Junction-to-Ambient) (Note 3)	0 Ifmp 500 Ifmp	QFN-16 QFN-16	42 35	$^{\circ}\text{C}/\text{W}$ $^{\circ}\text{C}/\text{W}$
θ_{JC}	Thermal Resistance (Junction-to-Case)	(Note 3)	QFN-16	4	$^{\circ}\text{C}/\text{W}$
T_{sol}	Wave Solder Pb-Free			265	$^{\circ}\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

3. JEDEC standard multilayer board – 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

NB6L11M

Table 4. DC CHARACTERISTICS, Multi-Level Inputs $V_{CC} = 2.375\text{ V to }3.63\text{ V}$, $V_{EE} = 0\text{ V}$, or $V_{CC} = 0\text{ V}$, $V_{EE} = -2.375\text{ V to }-3.63\text{ V}$, $T_A = -40^\circ\text{C to }+85^\circ\text{C}$

Symbol	Characteristic	Min	Typ	Max	Unit
POWER SUPPLY CURRENT					
I_{CC}	Power Supply Current (Inputs and Outputs Open)	45	60	75	mA
CML OUTPUTS (Notes 4 and 5)					
V_{OH}	Output HIGH Voltage $V_{CC} = 3.3\text{ V}$ $V_{CC} = 2.5\text{ V}$	$V_{CC} - 40$ 3260 2460	$V_{CC} - 10$ 3290 2490	V_{CC} 3300 2500	mV
V_{OL}	Output LOW Voltage $V_{CC} = 3.3\text{ V}$ $V_{CC} = 2.5\text{ V}$	$V_{CC} - 500$ 2800 2000	$V_{CC} - 400$ 2900 2100	$V_{CC} - 300$ 3000 2200	mV
DIFFERENTIAL INPUT DRIVEN SINGLE-ENDED (see Figures 4 and 5) (Note 6)					
V_{th}	Input Threshold Reference Voltage Range (Note 7)	1125		$V_{CC} - 75$	mV
V_{IH}	Single-ended Input HIGH Voltage	$V_{th} + 75$		V_{CC}	mV
V_{IL}	Single-ended Input LOW Voltage	V_{EE}		$V_{th} - 75$	mV
V_{ISE}	Single-ended Input Voltage Amplitude ($V_{IH} - V_{IL}$)	150		2800	mV
VREFAC					
V_{REFAC}	Output Reference Voltage ($V_{CC} \geq 2.5\text{ V}$)	$V_{CC} - 1525$	$V_{CC} - 1425$	$V_{CC} - 1325$	mV
DIFFERENTIAL INPUTS DRIVEN DIFFERENTIALLY (see Figures 6, 7 and 8) (Note 8)					
V_{IHD}	Differential Input HIGH Voltage	$V_{EE} + 1200$		V_{CC}	mV
V_{ILD}	Differential Input LOW Voltage	V_{EE}		$V_{CC} - 100$	mV
V_{ID}	Differential Input Voltage ($V_{IHD} - V_{ILD}$)	$V_{EE} + 100$		$V_{CC} - V_{EE}$	mV
V_{CMR}	Input Common Mode Range (Differential Configuration) (Note 9)	$V_{EE} + 950$		$V_{CC} - 50$	mV
I_{IH}	Input HIGH Current D / \bar{D} , (V_{TD}/\bar{V}_{TD} Open)	-150		150	μA
I_{IL}	Input LOW Current D / \bar{D} , (V_{TD}/\bar{V}_{TD} Open)	-150		150	μA
TERMINATION RESISTORS					
R_{TIN}	Internal Input Termination Resistor	40	50	60	Ω
R_{TOUT}	Internal Output Termination Resistor	40	50	60	Ω

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- CML outputs loaded with $50\ \Omega$ to V_{CC} for proper operation.
- Input and output parameters vary 1:1 with V_{CC} .
- V_{th} , V_{IH} , V_{IL} , and V_{ISE} parameters must be complied with simultaneously.
- V_{th} is applied to the complementary input when operating in single-ended mode.
- V_{IHD} , V_{ILD} , V_{ID} and V_{CMR} parameters must be complied with simultaneously.
- V_{CMR} min varies 1:1 with V_{EE} . V_{CMR} maximum varies 1:1 with V_{CC} . The V_{CMR} range is referenced to the most positive side of the differential input signal.

NB6L11M

Table 5. AC CHARACTERISTICS $V_{CC} = 2.375\text{ V to }3.63\text{ V}$, $V_{EE} = 0\text{ V}$, or $V_{CC} = 0\text{ V}$, $V_{EE} = -2.375\text{ V to }-3.63\text{ V}$, $T_A = -40^\circ\text{C to }+85^\circ\text{C}$; (Note 10)

Symbol	Characteristic	Min	Typ	Max	Unit
V_{OUTPP}	Output Voltage Amplitude (@ $V_{INPP(MIN)}$) (Note 15) (See Figure 9)	$f_{in} \leq 3.0\text{GHz}$ 230 $f_{in} \leq 3.5\text{ GHz}$ 190 $f_{in} \leq 4.0\text{ GHz}$ 150	380 320 270		mV
t_{PD}	Propagation Delay D to Q	175	225	325	ps
t_{SKEW}	Duty Cycle Skew (Note 11) Within Device Skew Device to Device Skew (Note 12)		5.0 3.0	15 15 80	ps
t_{DC}	Output Clock Duty Cycle (Reference Duty Cycle = 50%) $f_{in} \leq 4.0\text{GHz}$	40	50	60	%
t_{JITTER}	RMS Random Clock Jitter (Note 13) Peak-to-Peak Data Dependent Jitter (Note 14)		$f_{in} \leq 4\text{GHz}$ 0.2 $f_{in} \leq 4\text{Gb/s}$ 40	0.5	ps
V_{INPP}	Input Voltage Swing/Sensitivity (Differential Configuration) (Note 15)	150		2800	mV
t_r t_f	Output Rise/Fall Times @ 0.5 GHz (20% – 80%)		70	120	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

10. Measured by forcing V_{INPP} (MIN) from a 50% duty cycle clock source. All loading with an external $R_L = 50\ \Omega$ to V_{CC} . Input edge rates 40 ps (20% – 80%).

11. Duty cycle skew is measured between differential outputs using the deviations of the sum of T_{pw-} and T_{pw+} @ 0.5GHz.

12. Device to device skew is measured between outputs under identical transition @ 0.5 GHz.

13. Additive RMS jitter with 50% duty cycle clock signal.

14. Additive peak-to-peak data dependent jitter with input NRZ data at PRBS23.

15. Input and output voltage swing is a single-ended measurement operating in differential mode.

NB6L11M

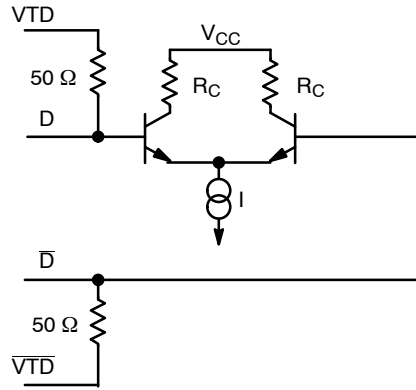


Figure 3. Input Structure

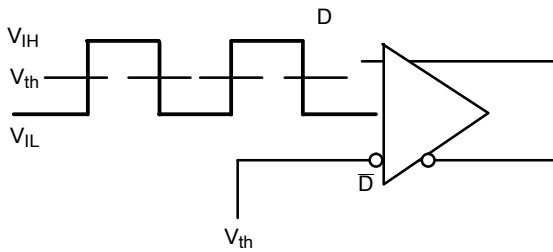


Figure 4. Differential Input Driven Single-Ended

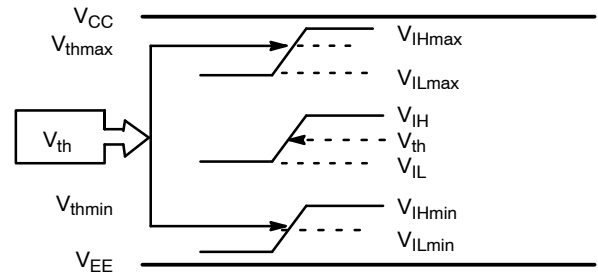


Figure 5. V_{th} Diagram

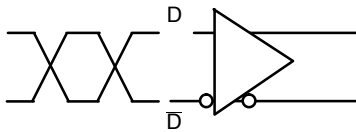


Figure 6. Differential Inputs Driven Differentially

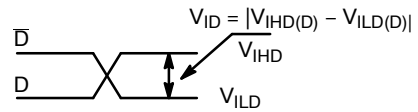


Figure 7. Differential Inputs Driven Differentially

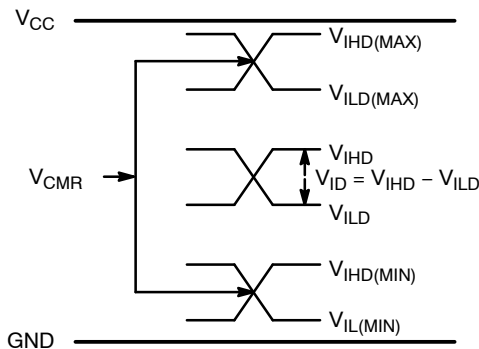


Figure 8. V_{CMR} Diagram

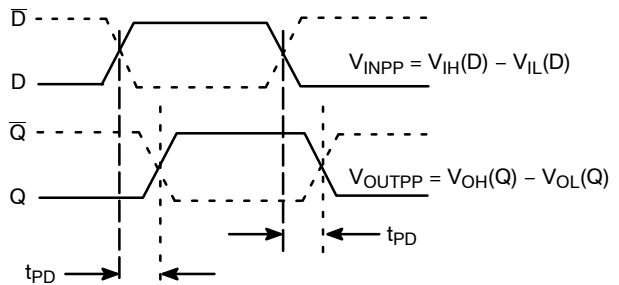


Figure 9. AC Reference Measurement

NB6L11M

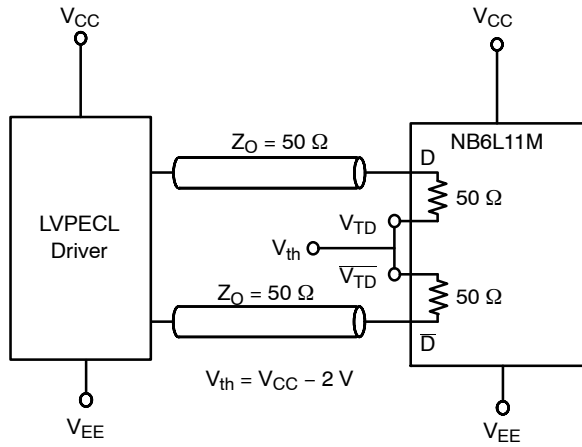


Figure 10. LVPECL Interface

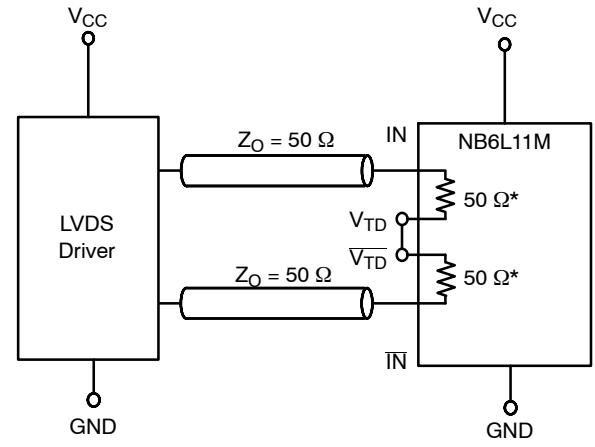


Figure 11. LVDS Interface

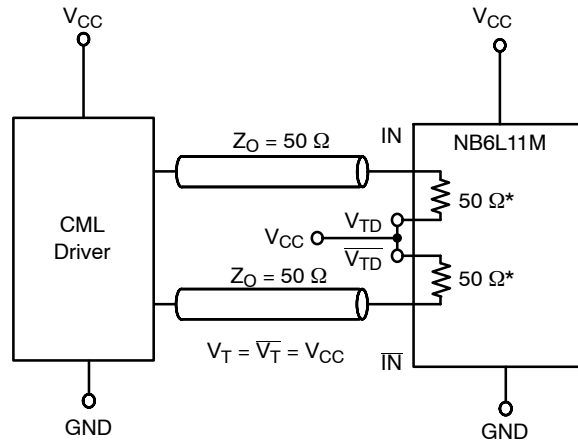


Figure 12. Standard 50 Ω Load CML Interface

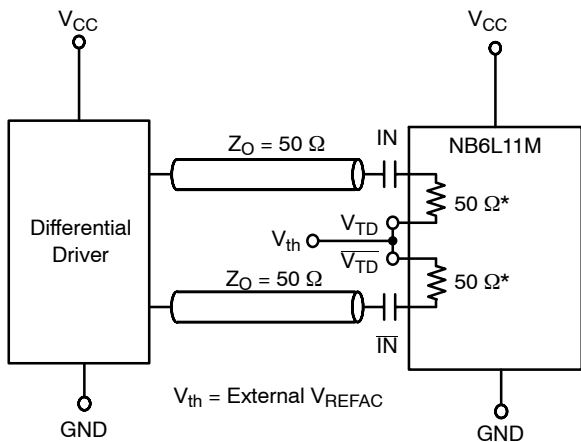


Figure 13. Capacitor-Coupled Differential Interface ($V_{TD}/\overline{V_{TD}}$ Connected to V_{REFAC} ; V_{REFAC} Bypassed to Ground with 0.1 μF Capacitor)

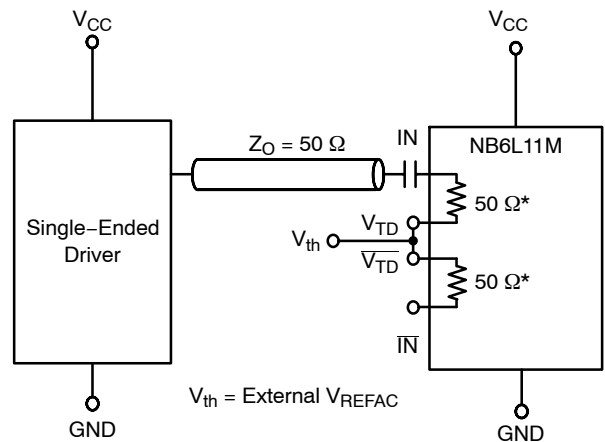


Figure 14. Capacitor-Coupled Single-Ended Interface ($V_T/\overline{V_T}$ Connected to V_{REFAC} ; V_{REFAC} Bypassed to Ground with 0.1 μF Capacitor)

NB6L11M

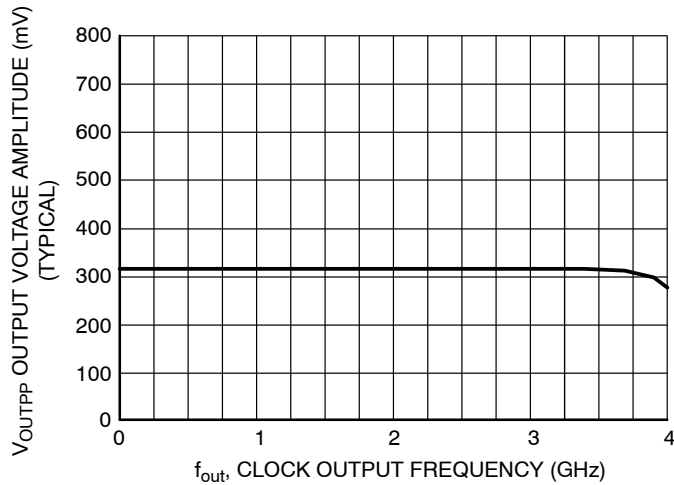


Figure 15. Output Voltage Amplitude (V_{OUTPP}) versus Output Frequency at Ambient Temperature (Typical)

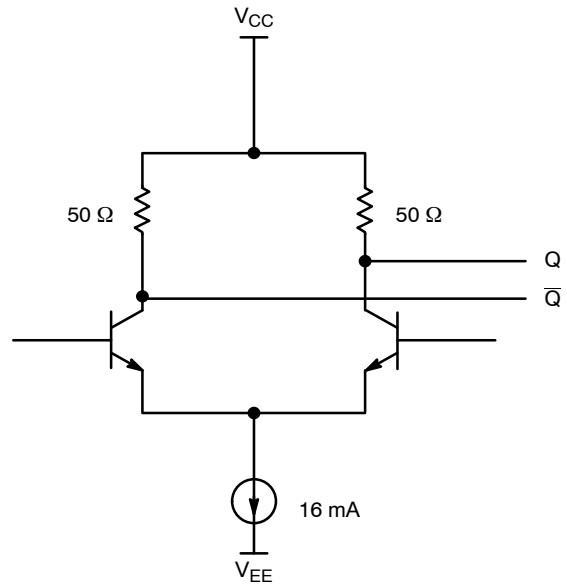


Figure 16. CML Output Structure

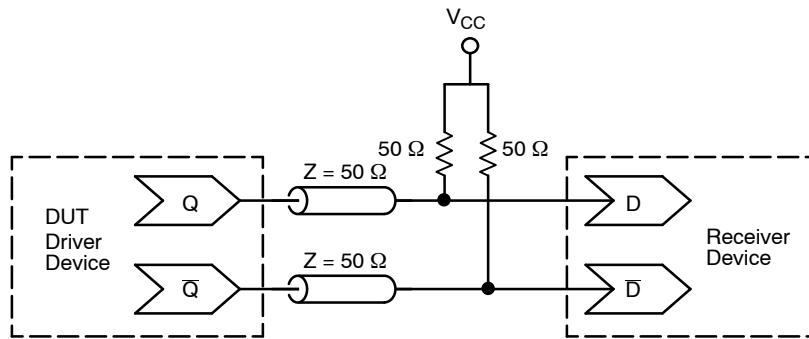


Figure 17. Typical CML Termination for Output Driver and Device Evaluation

ORDERING INFORMATION

Device	Package	Shipping [†]
NB6L11MMNG	QFN-16 (Pb-Free)	123 Units / Rail
	(Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

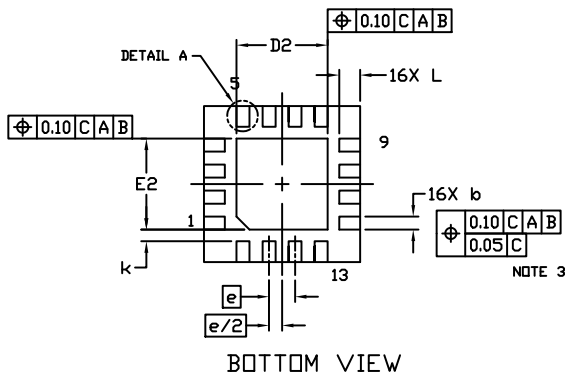
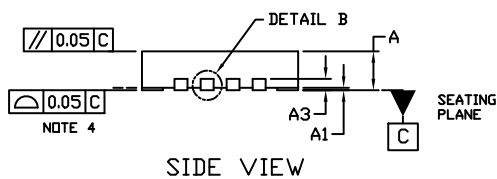
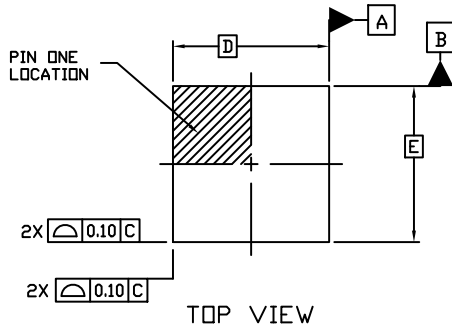
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 2:1

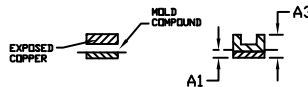
QFN16 3x3, 0.5P
CASE 485G
ISSUE G

DATE 08 OCT 2021

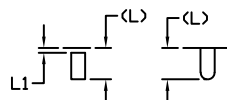


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.



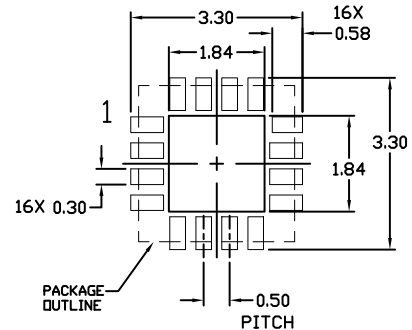
DETAIL B
ALTERNATE CONSTRUCTIONS



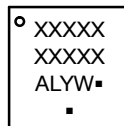
DETAIL A
ALTERNATE TERMINAL CONSTRUCTIONS

DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
A	0.80	0.90	1.00
A1	0.00	0.03	0.05
A3	0.20 REF		
b	0.18	0.24	0.30
D	3.00 BSC		
D2	1.65	1.75	1.85
E	3.00 BSC		
E2	1.65	1.75	1.85
e	0.50 BSC		
k	0.18 TYP		
L	0.30	0.40	0.50
L1	0.00	0.08	0.15

MOUNTING FOOTPRINT



GENERIC MARKING DIAGRAM*



- XXXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON04795D	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	QFN16 3X3, 0.5P	PAGE 1 OF 1

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation
onsemi Website: www.onsemi.com

ONLINE SUPPORT: www.onsemi.com/support

For additional information, please contact your local Sales Representative at www.onsemi.com/support/sales